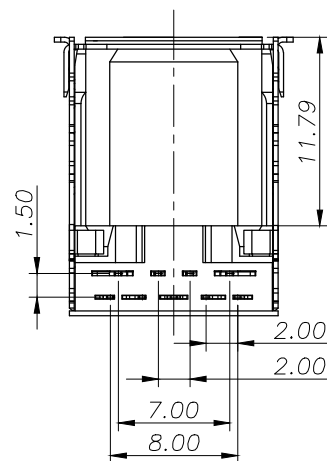
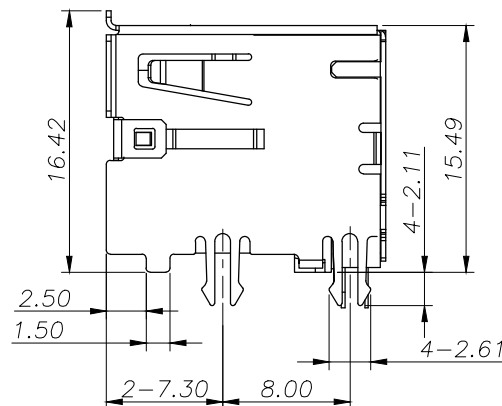
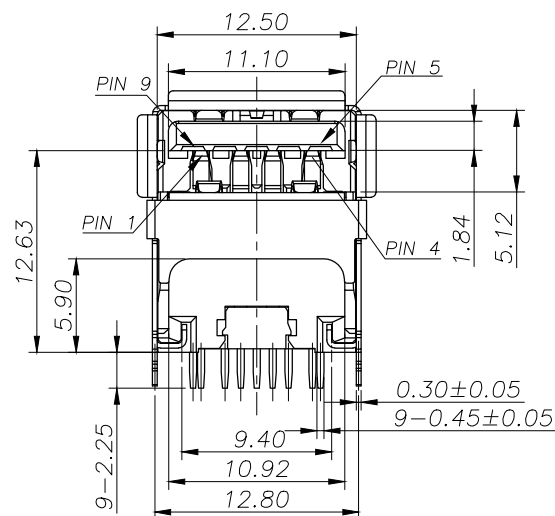
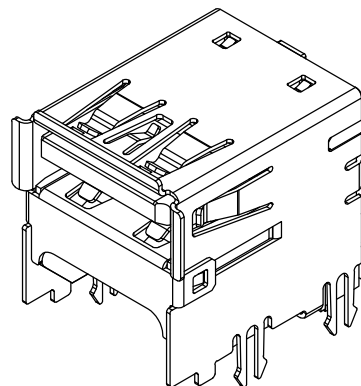
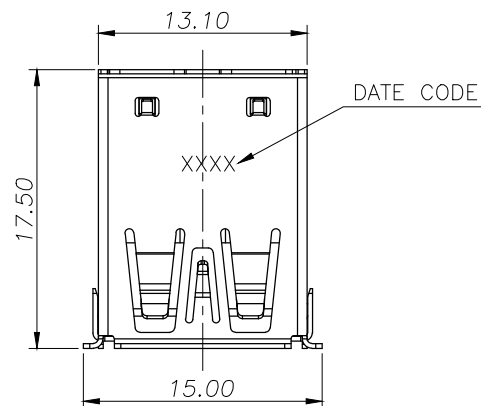




REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
02	--	Add Color code	2020.08.07	YIN
03	--	Modify the remark	2021.03.10	YIN

NOTE:

1.MATERIAL SPECIFICATION:

- 02 1-1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,BLUE(300C),UL94 V-0.
1-2.COVER:HIGH TEMPERATURE RESISTANT PLASTIC BLACK,UL94 V-0.
1-3.FRAME:HIGH TEMPERATURE RESISTANT PLASTIC BLACK,UL94 V-0.
03 1-4.USB3.1 CONTACTS: BRASS.
1-5.USB2.0 CONTACTS: PHOSPHOR BRONZE .
1-6.FRONT SHELL: STAINLESS STEEL.
1-7.BACK SHELL: COLD-ROLLED CARBON STEEL.
1-8.IRON SHELL: STAINLESS STEEL.

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.
Au15u"MIN PLATED ON THE FUNCTIONAL AREA OF CONTACT.
100u" MIN TIN PLATED ON SOLDER AREA.

2-2.FRONT SHELL:

SHELL PEG Sn PRO_SOLDER.

2-3.BACK SHELL:

Ni50u"MIN. UNDER PLATED OVER ALL.

2-4.IRON SHELL:

CLEARING ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 3.5kgf MAX
3-2.REMOVAL FORCE: 1.0kgf MIN,INITIALLY
3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1.CONTACT RESISTANCE:30mΩ MAX FOR INITIAL.
4-2.CONTACT CURRENT RATING:1.8A FOR VBUS AND GND PIN;
OTHER PINS:0.25A/PIN;
4-3.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
4-4.INSULATION RESISTANCE: 100MΩ MIN.
4-5.OPERATING TEMPERATURE:-55°C~+85°C.

5.IR REFLOW:

WAVE SOLDER 260°C 5SECONDS.

6.HF COMPLIANT

7.DATE CODE:XX XX

WEEK
YEAR

DIM	TOL	DIM	DEG
X	±0.50	X°	±8°
X.X	±0.35	X.X°	±5°
X.XX	±0.25	X.XX°	±3°
X.XXX	±0.15	X.XXX°	±2°
DESIGN:	YIN	2021.03.10	
CHECK:			
APPROVED			

JOINSOO建舜電子

FILE:	DRAW NAME:
DRAW NO.	USB3.1 SINGLE HIGH RISE TYPE
P/N: 12HU-306E-A6BT	
UNIT: mm	SCALE: 1:1
REV: 03	SHEET: 1/3
MODEL:	